

UW1141C

1608 (h=0.7 mm) Type White LED

Features

Package	1608 (h=0.7 mm) Type, Pale yellow resin
Product features	<ul style="list-style-type: none"> Outer Dimension 1.6 x 0.8 x 0.7mm(L x W x H) Temperature range <ul style="list-style-type: none"> Storage Temperature : -40 ~ 100 Operating Temperature : -40 ~ 85 No lead package and lead-free soldering compatible
Chromaticity coordinates	$x = 0.31\text{TYP.}$, $y = 0.32\text{TYP.}$ (Condition : $I_F=10\text{mA}$)
Half Intensity Angle	$\theta_x = 120 \text{ deg.}$, $\theta_y = 156 \text{ deg.}$
Die materials	InGaN
Rank grouping parameter	Sorted by luminous intensity and chromaticity per rank taping
Assembly method	Auto pick & place machine (Auto Mounter)
Soldering methods	Reflow soldering, TTW (Through The Wave) soldering and manual soldering
Taping and reel	4,000pcs per reel in a 8mm width tape. (Standard) Reel diameter: $\phi 180\text{mm}$
ESD	1kV (HBM)

Recommended Applications

Cellular Phone, Electric Household Appliances, OA/FA, Other General Applications



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1608 (h=0.7 mm) Type White LED

Color and Luminous Intensity

(Ta=25°C)

Part No.	Material	Emitted Color	Lens Color	Luminous Intensity		
				Iv (mcd)		
				MIN.	TYP.	I _F
UW1141C	InGaN	White	Pale Yellow	55	100	10

Absolute Maximum Ratings

(Ta=25°C)

Item	Symbol	Absolute Maximum Ratings	Unit
Power Dissipation	P_d	84	mW
Forward Current	I_F	20	mA
Pulse Forward Current ※1	I_{FRM}	48	mA
Derating (Ta=25°C or higher)	I_F	0.28	mA/
	I_{FRM}	0.69	mA/
Reverse Voltage	V_R	5	V
Operating Temperature	T_{opr}	-40 ~ +85	
Storage Temperature	T_{stg}	-40 ~ +100	

※1 I_{FRM} Measurement condition : Pulse Width ≤ 1 ms., Duty $\leq 1/20$.

Electro-Optical Characteristics

(Ta=25°C)

Item	Condition	Symbol	Characteristics		Unit
Forward Voltage	I _F =10mA	V _F	TYP.	3.5	V
			MAX.	4.0	
Reverse Current	V _R =5V	I _R	MAX.	100	μ A
Half Intensity Angle	I _F =10mA	2θ 1/2	TYP.	120(θ _x)	deg.
				156(θ _y)	
Chromaticity Coordinates	I _F =10mA	x	TYP.	0.31	-
		y	TYP.	0.32	-

Luminous Intensity Rank

(Ta=25°C)

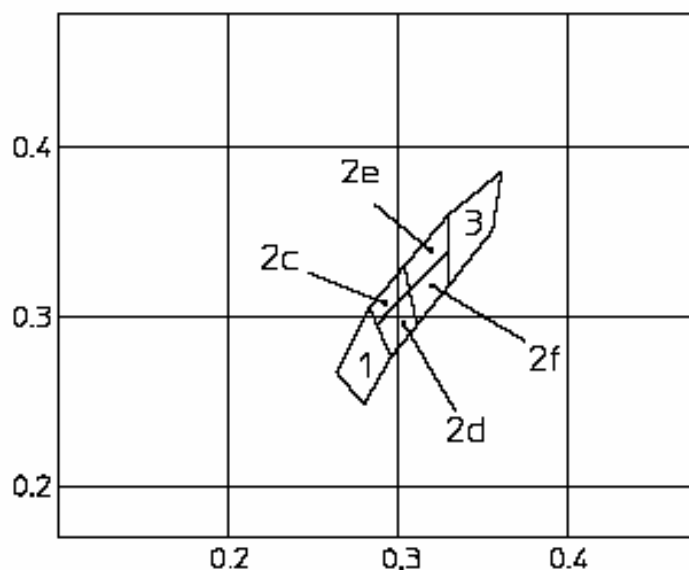
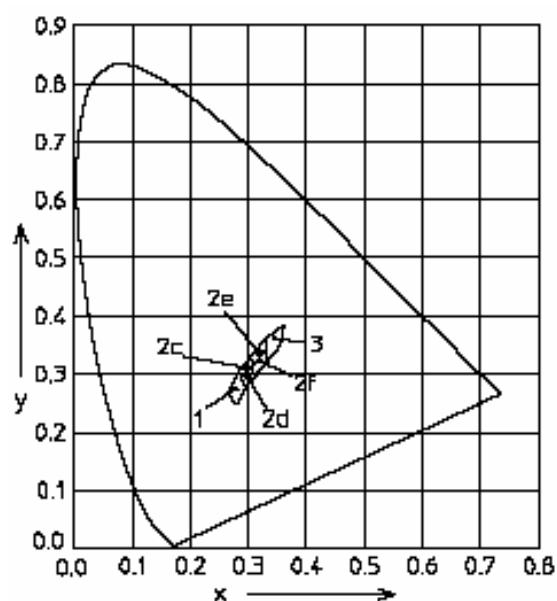
Intensity Tolerance each Rank : +/-10%

Rank	I _V (mcd)		Condition
	MIN.	MAX.	
A	55	90	I _F =10mA
B	90	140	
C	140	-	

Please contact our sales staff concerning rank designation.

Sorting Chart for Chromaticity Coordinates

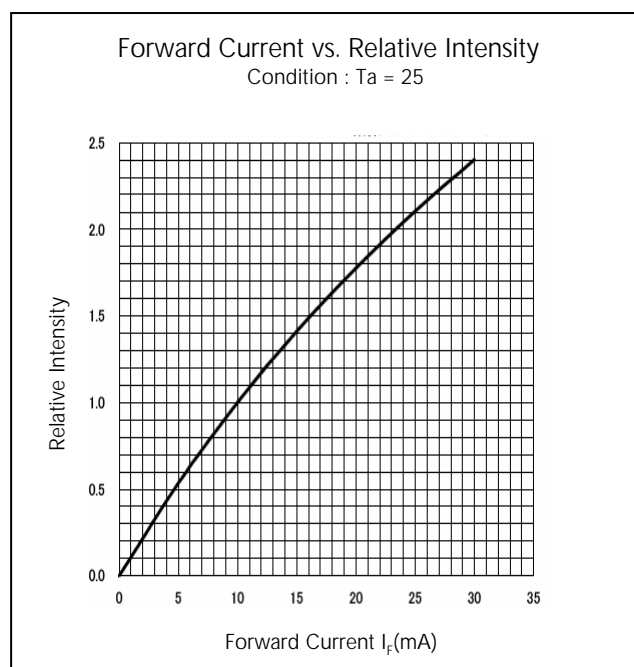
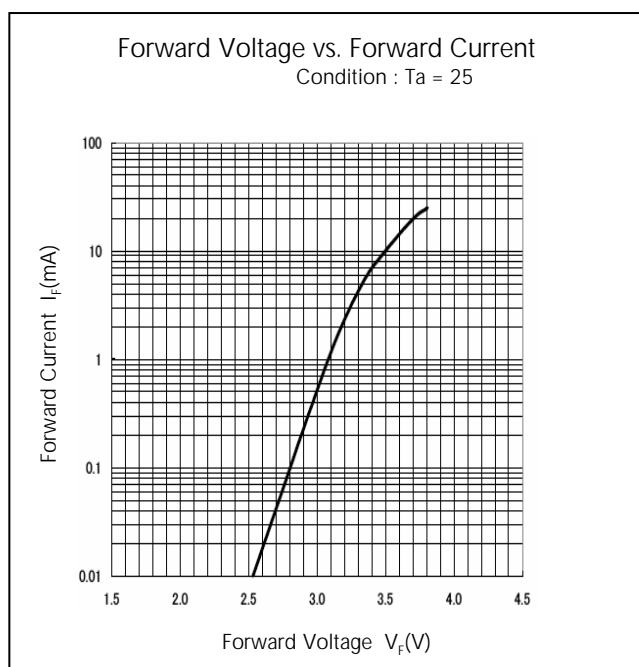
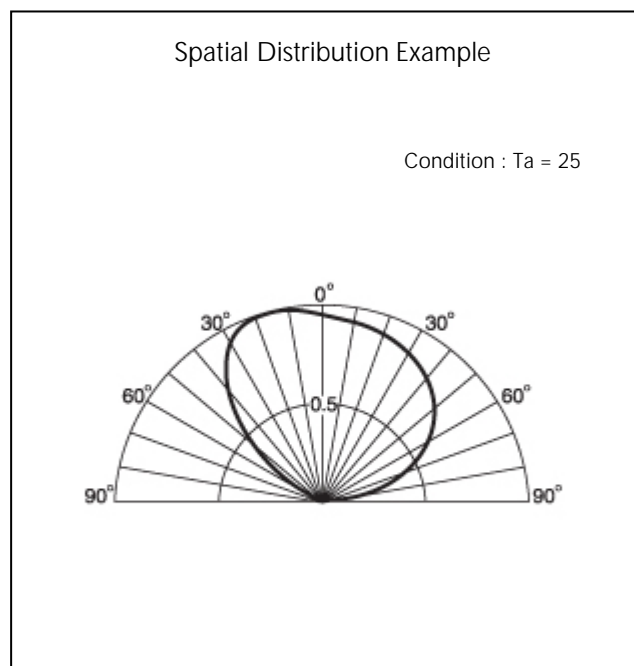
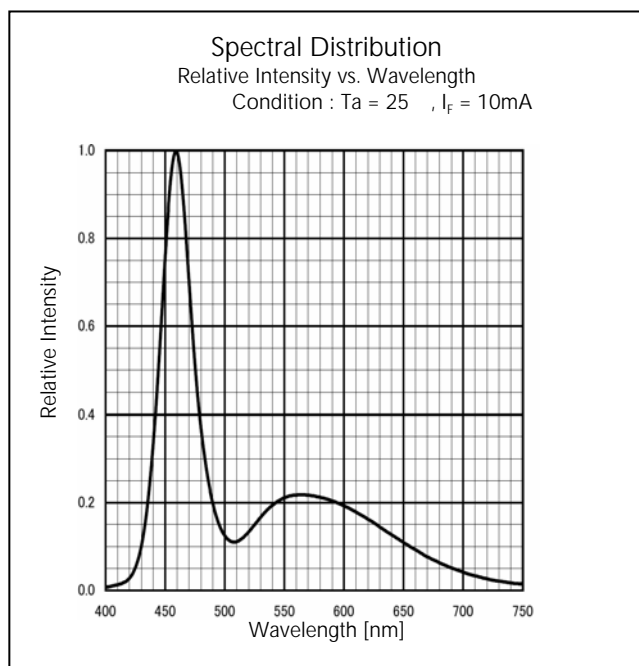
(Ta=25°C)


Chromaticity Coordinates Tolerance Each Rank : ± 0.02

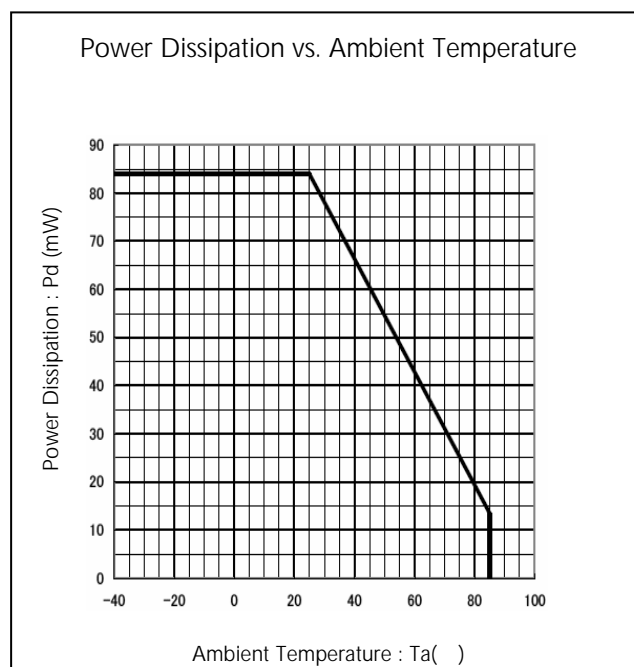
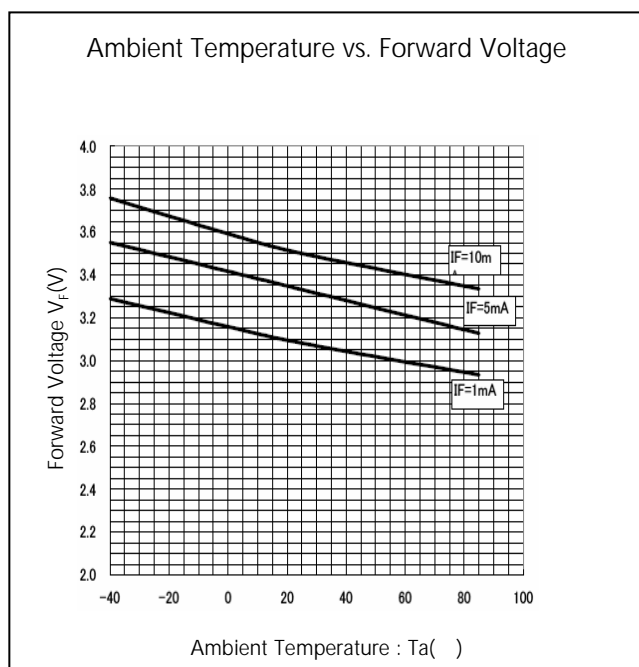
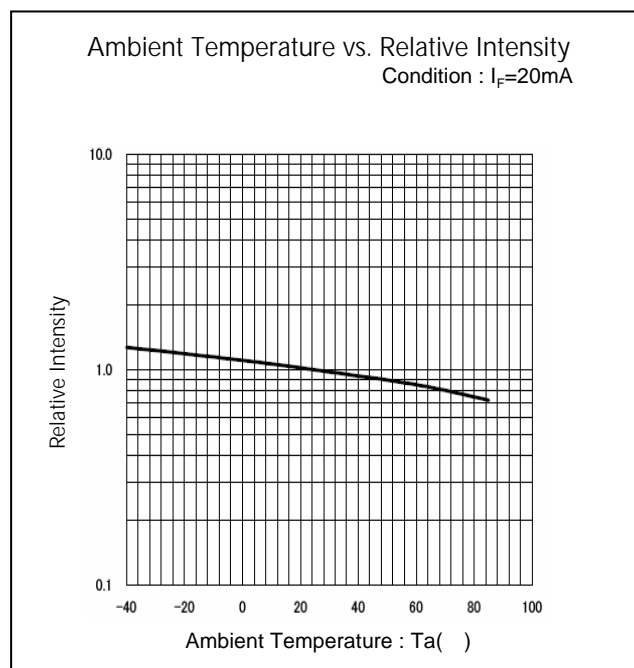
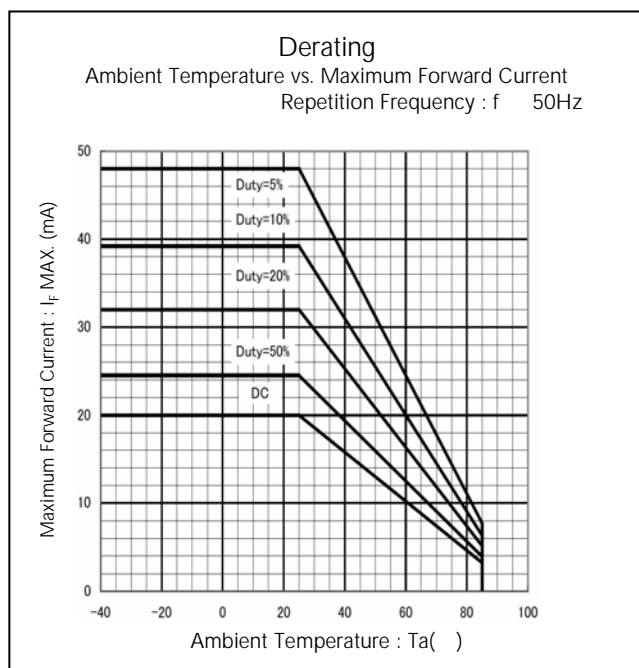
Rank	LEFT DOWN point		LEFT UP point		RIGHT UP point		RIGHT UP point	
	x	y	x	y	x	y	x	y
1	0.280	0.248	0.264	0.267	0.283	0.305	0.296	0.276
2c	0.287	0.295	0.283	0.305	0.304	0.330	0.307	0.315
2d	0.296	0.276	0.287	0.295	0.307	0.315	0.311	0.294
2e	0.307	0.315	0.304	0.330	0.330	0.360	0.330	0.339
2f	0.311	0.294	0.307	0.315	0.330	0.339	0.330	0.318
3	0.330	0.318	0.330	0.360	0.361	0.385	0.356	0.351

Please contact our sales staff concerning rank designation.

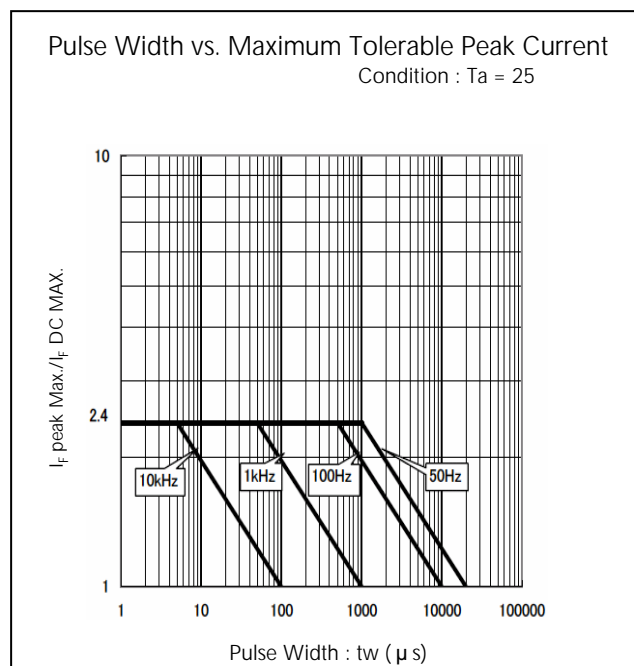
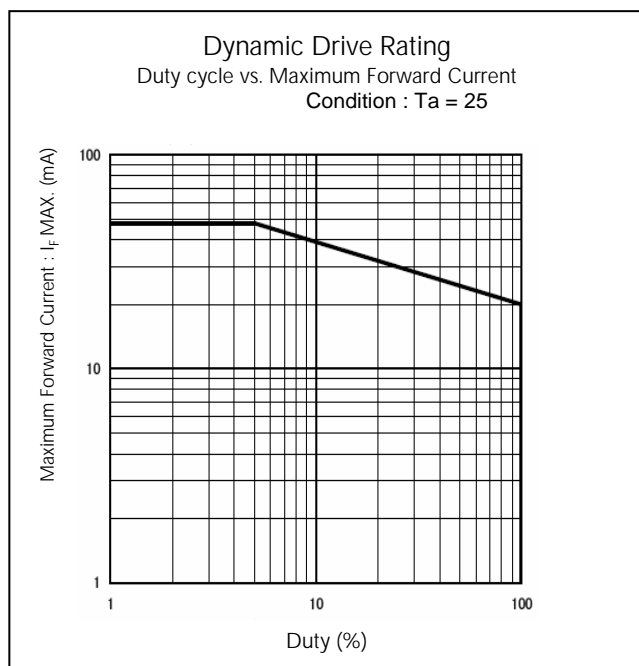
Technical Data



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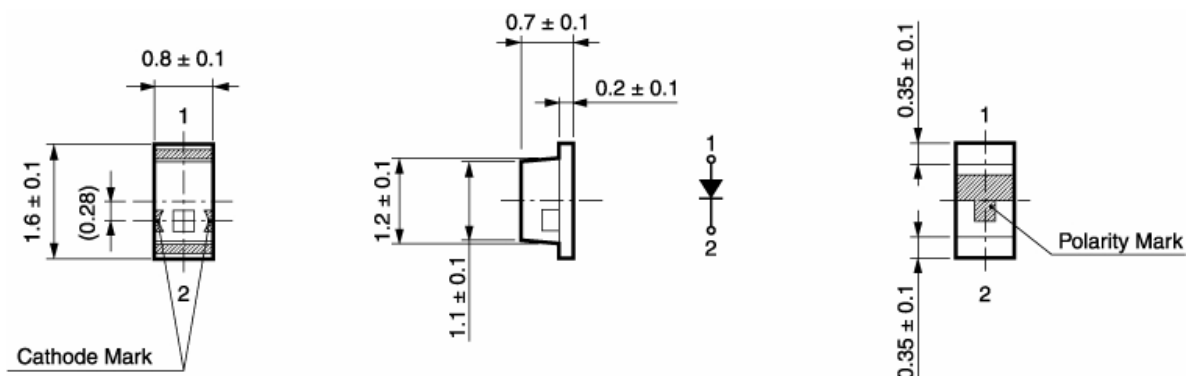
Technical Data



Package Dimensions

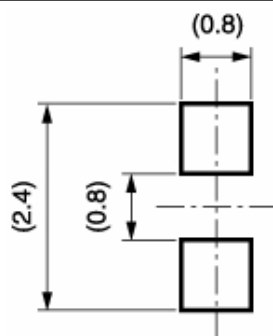
(Unit: mm)

Weight: (1.40)mg



Recommended Soldering Pattern

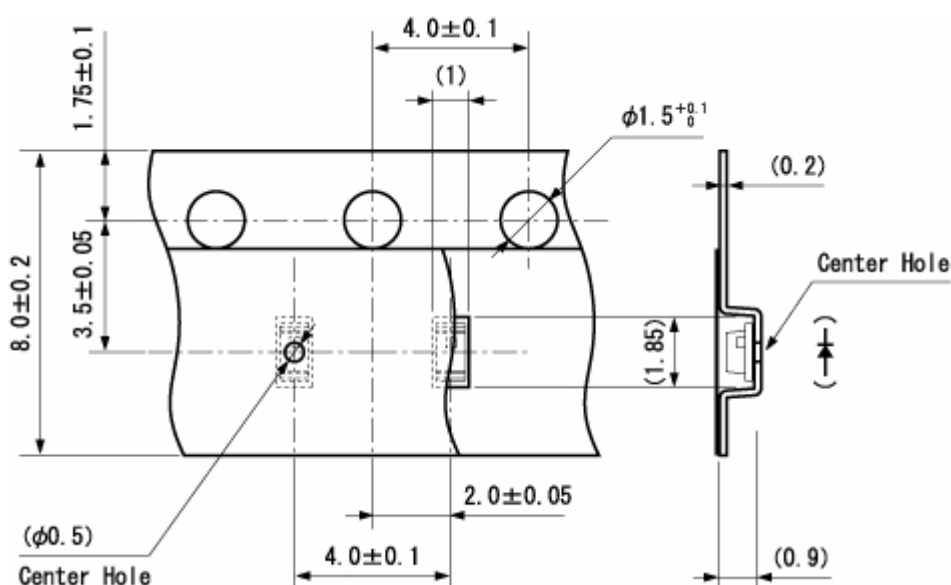
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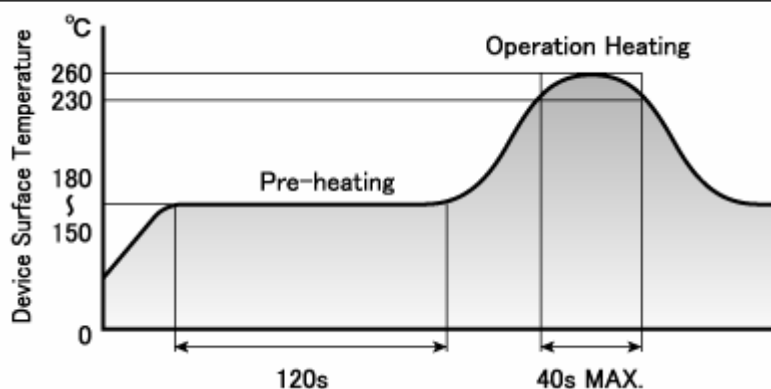
Taping Specification

(Unit: mm)

Quantity: 4,000pcs/ reel (standard)



Reflow Soldering Conditions



- 1) The above profile temperature gives the maximum temperature of the LED resin surface. Please set the temperature so as to avoid exceeding this range.
- 2) Total times of reflow soldering process shall be no more than 2 times. When the second reflow soldering process is performed, intervals between the first and second reflow should be short as possible (while allowing some time for the component to return to normal temperature after the first reflow) in order to prevent the LED from absorbing moisture.
- 3) Temperature fluctuation to the LED during the pre-heating process shall be minimized. (6 maximum)

TTW (Through The Wave) soldering Conditions

Pre-heating	120 60 s	(MAX.) (MAX.)
Solder Bath Temp.	265	(MAX.)
Dipping Time	5 s	(MAX.)

- 1) The dip soldering process shall be 2 times maximum.
- 2) The product shall be cooled to normal temperature before the second dipping process.

Manual Soldering Conditions

Iron tip temp.	350	(MAX.)
Soldering time and frequency	3 s 1 time	(MAX.) (MAX.)

Reliability Testing Result

Reliability Testing Result	Applicable Standard	Testing Conditions	Duration	Failure
Room Temp. Operating Life	EIAJ ED-4701/100(101)	Ta = 25°C, If = Maximum Rated Current	1,000 h	0/25
Resistance to Soldering Heat	EIAJ ED-4701/300(302)	260±5°C	5sec	0/25
Temperature Cycling	EIAJ ED-4701/100(105)	Minimum Rated Storage Temperature(30min) ~Normal Temperature(15min) ~Maximum Rated Storage Temperature(30min) ~Normal Temperature(15min)	5 cycles	0/25
Wet High Temp. Storage Life	EIAJ ED-4701/100(103)	Ta = 60±2°C, RH = 90±5%	1,000 h	0/25
High Temp. Storage Life	EIAJ ED-4701/200(201)	Ta = Maximum Rated Storage Temperature	1,000 h	0/25
Low Temp. Storage Life	EIAJ ED-4701/200(202)	Ta = Minimum Rated Storage Temperature	1,000 h	0/25
Vibration, Variable Frequency	EIAJ ED-4701/400(403)	98.1m/s ² (10G), 100 ~ 2KHz sweep for 20min., XYZ each direction	2 h	0/10

Failure Criteria

Items	Symbols	Conditions	Failure criteria
Luminous Intensity	Iv	If Value of each product Luminous Intensity	Testing Min. Value < Spec. Min. Value x 0.5
Forward Voltage	V _F	If Value of each product Forward Voltage	Testing Max. Value ≥ Spec. Max. Value x 1.2
Reverse Current	I _R	V _R = Maximum Rated Reverse Voltage V	Testing Max. Value ≥ Spec. Max. Value x 2.5
Cosmetic Appearance	-	-	No notable, decoloration, deformation and cracking

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